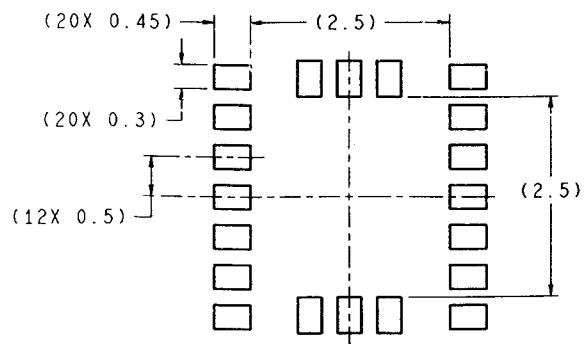
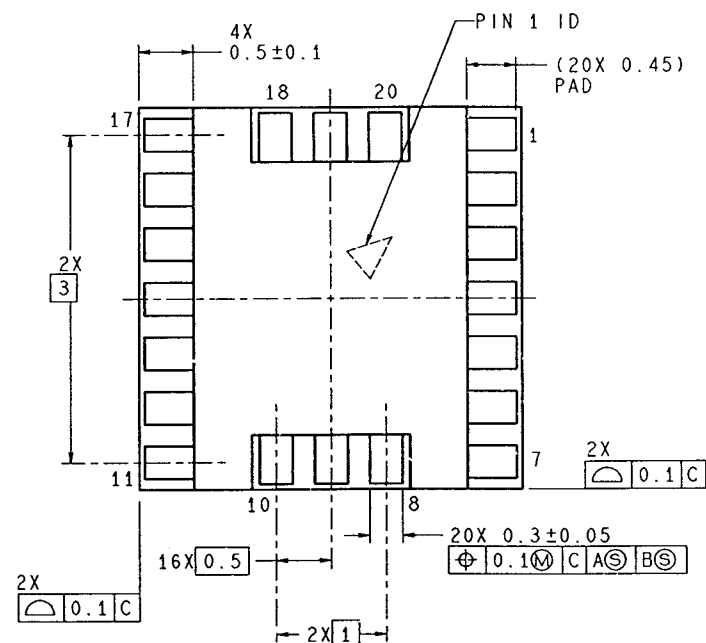
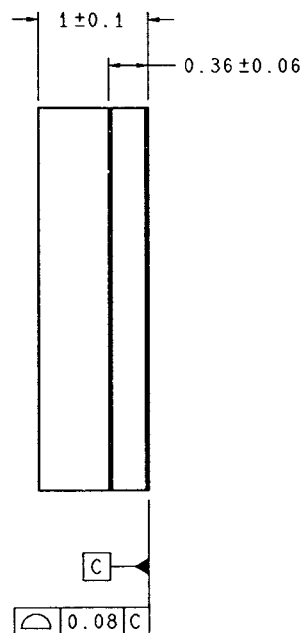
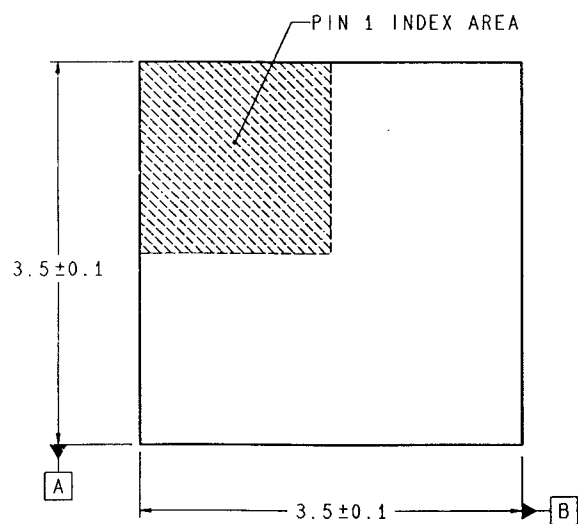




RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS

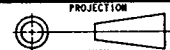


DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

1. MATERIAL: BT RESIN CCL-HL832 WITH TAIYO PSR4000 AUS5 SOLDER MASK.
2. PLATING: Cu 15 TO 20 MICROMETERS
Ni 10 ± 5 MICROMETERS
Au 1 ± 0.5 MICROMETER
3. REFERENCE JEDEC REGISTRATION MO-208, VARIATION CCEA-1, DATED DECEMBER 1999.

REVISIONS			
LTR	DESCRIPTION	E.C.N.	DATE
A	RELEASE TO DOCUMENT CONTROL	12419	03/07/2000

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRWN	T. LEQUANG	03/06/2000		
DES. CHK.	Y. S. S. S. S.	03/07/2000	CSP, PLASTIC, LAMINATED, 3.5 X 3.5 X 1.0 mm BODY, 20 L, 0.5 mm PITCH	
ENGR. CHK.	Tonyo Fridlyand	03/08/2000		
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		N/A	C	(SC)MKT-SLB20B
FORMERLY: N/A		SHEET 1 of 1		